PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Release of Security Interest in Intellectual Property

CONVEYING PARTY DATA

Name	Execution Date
The Bank of New York Mellon	05/27/2009

RECEIVING PARTY DATA

Name:	Magnachip Semiconductor, Inc. (formerly known as IC Media Corporation)
Street Address:	5201 Great American Parkway
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 17

Property Type	Number
Patent Number:	6750955
Patent Number:	7215834
Patent Number:	6894723
Patent Number:	7071981
Patent Number:	7085408
Patent Number:	6980286
Patent Number:	6137432
Patent Number:	6538695
Patent Number:	6763127
Patent Number:	7019776
Patent Number:	7113203
Patent Number:	7142734
Patent Number:	7149420
Patent Number:	7200279
Patent Number:	7212279

OP $680.00 6750955

Patent Number:	7266245
Patent Number:	7450161

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	002.D177
NAME OF SUBMITTER:	Robert Chang

Total Attachments: 6
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RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY

May 27, 2009

WHEREAS, Magnachip Semiconductor, Inc., a California corporation, formerly known as IC Media Corporation, a California corporation, formerly known as Magnachip Semiconductor, Inc., a Delaware corporation, MagnaChip Semiconductor LLC, a Delaware limited liability company, MagnaChip Semiconductor SA Holdings LLC, a Delaware limited liability company ("***Original Guarantors***"), and MagnaChip Semiconductor Finance Company, a Delaware corporation ("***MagnaChip Finance***"), (MagnaChip Finance, together with Original Guarantors, in such capacities and together with any successors in such capacities, the "***Pledgors***"), entered into that certain Security Agreement, dated as of December 23, 2004, and that certain Indenture Agreement, dated as of December 23, 2004, and that certain Joinder Agreement dated as of May 31, 2005 (collectively, the "***Bank of New York Mellon Security Agreement***") with The Bank of New York Mellon, as trustee, pledgee, assignee and secured party, together with its successors and assigns (the "***Trustee***"). WHEREAS the Security Agreement and Joinder Agreement was recorded in the United States Patent and Trademark Office on September 6, 2005 at Reel/Frame 016500/0697;

WHEREAS, Pledgors granted to the Trustee, under the terms of the Bank of New York Mellon Security Agreement, a continuing security interest (the "***Security Interest***") in favor of the Trustee in and to the intellectual property described in the Bank of New York Mellon Security Agreement, including without limitation the Transferred Intellectual Property (as defined below);

WHEREAS, Pledgors and the Trustee entered into the Bank of New York Mellon Security Agreement in connection with that certain Indenture Agreement dated as of December 23, 2004 (as amended, supplemented or otherwise modified from time to time, the "***Indenture***"), among MagnaChip Semiconductor, S.A., organized and existing under the laws of the Grand Duchy of Luxembourg, MagnaChip Finance (collectively, the "***Issuers***"), the Original Guarantors listed on the signature pages thereto or from time to time party thereto by execution of a joinder agreement (collectively, the "***Guarantors***"), The Bank of New York Mellon, in its capacity as trustee (in such capacity and together with any successors in such capacity, the "***Trustee***");

WHEREAS, MagnaChip Semiconductor, Inc. and Magnachip Semiconductor, Ltd., a limited liability company organized under the laws of Korea ("***MagnaChip Korea***") have entered into that certain Intersubsidiary Asset Transfer Agreement dated as of January 1, 2007 (the "***Intersubsidiary Asset Transfer Agreement***") pursuant to which MagnaChip Semiconductor, Inc., subject to the terms and conditions set forth therein, sold transferred, and assigned certain intellectual property rights to MagnaChip Korea;

WHEREAS, MagnaChip Korea and Crosstek Capital, LLC ("***COMPANY***") have entered into that certain Patent Sale Agreement dated as of April 15, 2009 (the "***Patent Sale Agreement***") pursuant to which MagnaChip Korea, subject to the terms and conditions set forth therein, sold, transferred and assigned certain intellectual property rights to COMPANY; and

WHEREAS, Pledgors, Issuers, Original Guarantors, Guarantors and MagnaChip Korea are collectively, the "***MagnaChip Entities***";

WHEREAS, the Trustee has agreed to release any and all of its right, title, and interest in and to any and all of the following (collectively, the "***Transferred Intellectual Property***"):

(a) the provisional patent applications, United States and foreign patent applications and patents listed in Exhibit A hereto (the "***Listed Patents***");

(b) all patents and patent applications (i) to which any of the Listed Patents directly or indirectly claims priority, (ii) for which any of the Listed Patents directly or indirectly forms a basis for priority, and/or (iii) that were co-owned applications that incorporate by reference, or are incorporated by reference into, the Listed Patents;

(c) all reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, requests for continuing examinations, divisions, registrations of any item in any of the foregoing categories (a) and (b);

(d) all foreign patents, patent applications, and counterparts relating to any item in any of the foregoing categories (a) through (c), including, without limitation, certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants or issuances;

(e) inventions, invention disclosures, and discoveries described in any of the Listed Patents and/or any item in the foregoing categories (b) through (d) that (i) are included in any claim in the Listed Patents and/or any item in the foregoing categories (b) through (d), (ii) are subject matter capable of being reduced to a patent claim in a reissue or reexamination proceeding brought on any of the Listed Patents and/or any item in the foregoing categories (b) through (d), and/or (iii) could have been included as a claim in any of the Listed Patents and/or any item in the foregoing categories (b) through (d);

(f)rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections, or other governmental grants or issuances of any type related to any item in any of the foregoing categories (a) through (e) and the inventions, invention disclosures, and discoveries therein;

(g) causes of action (whether known or unknown or whether currently pending, filed, or otherwise) and other enforcement rights under, or on account of, any of the Listed Patents and/or the rights described in the foregoing categories (b) through (f), including, without limitation, all causes of action and other enforcement rights for (i) damages, (ii) injunctive relief, and (iii) any other remedies of any kind for past, current and future infringement; and

(h) rights to collect royalties or other payments under or on account of any of the Listed Patents and/or any item in any of the foregoing categories (b) through (g), except for proceeds of sale paid to MagnaChip Korea by the COMPANY under the Patent Sale Agreement related to the Listed Patents (the "***Sale Proceeds***").

NOW, THEREFORE, in consideration of the foregoing, and for other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and intending to be legally bound, the Trustee hereby irrevocably and unconditionally waives and releases the Security Interest and any and all right, title and interest of any kind that exists today and may exist in the future in and to the Transferred Intellectual Property, hereby waives and relinquishes all its rights, powers, privileges and remedies with respect to the MagnaChip Entities and their successors and assigns under the Bank of New York Mellon Security Agreement with respect to the Transferred Intellectual Property and hereby releases

the MagnaChip Entities and their respective successors and assigns from all covenants, obligations, liabilities and warranties under the Bank of New York Mellon Security Agreement with respect to the Transferred Intellectual Property. Notwithstanding the foregoing, the Trustee retains its security interest in and to the Sale Proceeds. Upon any of the MagnaChip Entities' request, and at such MagnaChip Entities' sole cost and expense, the Trustee agrees to execute and provide any additional documents necessary to fully release and waive all its right, title and interest of any kind that exists today and may exist in the future in and to the Transferred Intellectual Property and to register such releases and waivers with patent offices and government offices worldwide (including, without limitation, any additional documents necessary to register this Release Of Security Interest In Intellectual Property with the Korean Intellectual Property Office and the United States Patent and Trademark Office). The Trustee agrees not to establish any new security interest in the Transferred Intellectual Property.

Trustee hereby authorizes the MagnaChip Entities' authorized representative to file UCC Termination Statements with the applicable filing office(s) and to file this Release Of Security Interest In Intellectual Property in the applicable patent office(s) in order to memorialize the release of any security interest of Trustee in the Transferred Intellectual Property.

This Release Of Security Interest In Intellectual Property is governed by the law of the State of Delaware, excluding its choice of law principles to the contrary. This Release Of Security Interest In Intellectual Property shall be binding upon Trustee, any collateral trustees, their successors and assigns and inures to the benefit of the MagnaChip Entities and their successors and assigns.

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IN WITNESS WHEREOF, the undersigned has executed this Release Of Security Interest In Intellectual Property as of the date first set forth above.

The Bank of New York Mellon, as Trustee

By: _____

Print Name: David M. Hover

Title: Vice President

Exhibit A
Listed Patents

Patent No.	Application No.	Title	Country	Filing Date
6,137,432	09/187,308	Low-Power Column Parallel ADC In CMOS Image Sensors	US	11/4/1998
6,538,695	09/185,796	On-Chip Fixed-Pattern Noise Calibration For Cmos Image Sensors	US	11/4/1998
6,763,127	09/680,999	Apparatus And Method For Fingerprint Recognition System	US	10/6/2000
6,750,955	10/100,689	Compact Optical Fingerprint Sensor And Method	US	3/14/2002
ZL03121648.X	CN03121648.X	Micro-Optical Fingerprint Sensor And Method For Imaging Fingerprint	CN	3/13/2003
6,980,286	10/002,420	Ultra-Thin Optical Fingerprint Sensor With Anamorphic Optics	US	10/25/2001
	CN02144072.7	Ultra Thin Optical Image Sensor And Its Make-Up Method	CN	9/29/2002
7,142,734	10/026,094	2D Imaging Data Collection Sensor With Matching Illuminator	US	12/21/2001
ZL02157431.6	CN02157431.6	Two-Dimensional Image Data Collecting Device With Matching Lighting And Collecting Method	CN	12/19/2002
7,266,245	10/112,265	Image Signal Compression Method And System	US	3/28/2002
7,215,834	10/165,716	Congfigurable Image Processing Driver	US	6/7/2002
7,085,408	10/197,951	Method And System For Testing Image Sensor System-On-Chip	US	7/16/2002
7,071,981	10/188,601	Image Sensing System And Method	US	7/1/2002
7,113,203	10/141,450	Method And System For Single-Chip Camera	US	5/7/2002
7,212,279	10/153,021	Biometric Identity Verifiers And Methods	US	5/20/2002
ZL03136428.4	CN03136428.4	System And Method Of Checking Biological Identity	CN	5/19/2003
7,019,776	10/223,157	Method And System For Automatic White Balancing	US	8/16/2002
7,200,279	10/660,864	Method And System For Image Chroma Suppression	US	9/11/2003
	11/051,320	Method and System for Fixing Defective Pixels	US	
	11/004,465	Microlens Alignment Procefures in CMOS Image Sensor Design	US	
	11/004,376	Image Pixel Design to Enhance the Uniformity of Intensity Distribution on Digital Image Sensors	US	
7,450,161	11/003,824	System And Method To Enhance The Uniformity Of Intensity Distribution On Digital Imaging Sensors	US	12/2/2004
	10/976,693	CMOS Imaging Sensor with Optimized Photosensor Shape	US	
7,149,420	10/973,540	Auto-Focusing Lens With Progressive Variable Focal Element	US	10/25/2004
7,291,876	11/067,039	Diffusion Bias Control For Improving Sensitivity Of CMOS Active Pixel Sensors	US	2/25/2005
7,508,430	11/061,349	Method for locally Reducing Row Noise	US	2/18/2005
	11/060,856	Method for Reducing Row Noise With Dark pixel Data	US	2/18/2005
	11/084,293	System for Digital Light Sources	US	3/16/2005

Patent No.	Application No.	Title	Country	Filing Date
7,297,916	11/064,346	Optically Improved CMOS Imaging Sensor Structure To Lower Imaging Lens Requirements	US	2/22/2005
6,894,723	09/960,166	Ranking-Based Automatic Dark Compensation Circuit	US	9/21/2001
	10/305,334	Programmable Register and Method for Sensor Wavetable Processing	US	
	10/228,882	Method of Improving Reset for Achieving a Noise-Free DSC Image for CMOS Image Sensors	US	
	10/263,533	A Method for Integrating CMOS Image Sensor for Video Applications Unisng Line Color Pattern	US	
	10/446,879	Method and System for Image Sensor Read-Out	US	
	10/464,924	Low-Leakage CMOS Image Pixel Structures Employing Asymmetrical Reset Transistor	US	
	10/654,198	Buried Contact Pixel (BCP) Structures for Enhanced Low Lux CMOS Imageing Sensors	US	
	10/977,231	Miniature Image Module with Detachable Lens Group	US	
	10/973,527	Mobile Zoom Imaging Module with Folded Optical Front	US	
	10/973,222	Automatic Bench Tester for Mobile Camera System	US	
	10/996,298	Miniature image Module with COB Feature Accomodation	US	
7,456,878	11/128,104	Method of Color Filter Design And Color Reproduction Under The Effect Of Pixel Crosstalk In CMOS Image Sensors	US	5/11/2005
	09/686,728	Apparatus and Method for a Fingerprint Sensing Device Having an Embedded Analog to Digital converter and Gamma Correction	US	
	11/313,976	Microlens Alignment Procedures In CMOS Image Sensor Design	US	12/20/2005
	11/314,452	Image Pixel Design to Enhance The Uniformity Of Intensity Distribution On Digital Image Sensors	US	12/20/2005